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(54) Title of the Invention: **Methodologies to improve reliability of transducer electrical interconnections**
Abstract Title: **Methodologies to improve reliability of transducer electrical interconnections**

(57) The present disclosure relates to methods and apparatuses measuring a property of a material. The apparatus may include a transducer comprising a first electrical conductor, a second electrical conductor, and a piezoelectric component configured to receive the two conductors. The piezoelectric component may include a cavity dimensioned to improve the strength of or reduce stress on an interconnection between piezoelectric component and at least one of the conductors. The method may include using one or more transducers measuring a property of a material. In some embodiments, the material may be an earth formation.

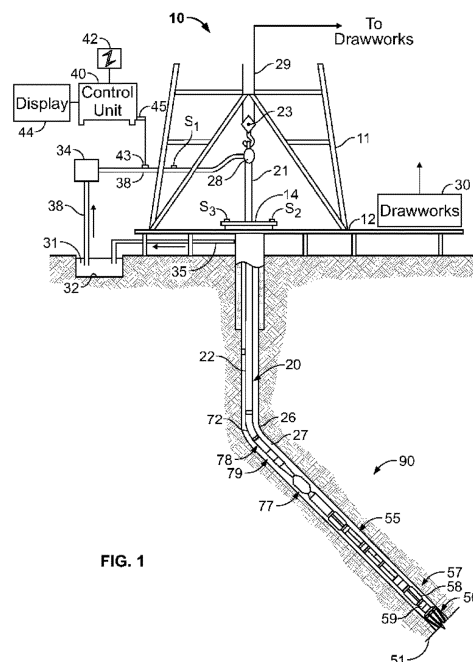


FIG. 1

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